

SEMITRANS[®] 3

Trench IGBT Modules

SKM300GB066D

Features*

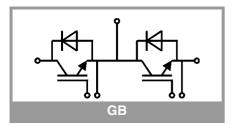
- Homogeneous Si
- Trench = Trenchgate technology
- V_{CE(sat)} with positive temperature coefficient
- + High short circuit capability, self limiting to 6 x ${\rm I_C}$

Typical Applications

- AC inverter drives
- UPS
- Electronic welders

Remarks

- Case temperature limited to $T_c = 125^{\circ}C$ max, recommended $T_{op} = -40 \dots$ +150°C
- Product reliability results are valid for $T_j \le 150^{\circ}C$
- Short circuit data: $t_p \le 6\mu$; $V_{GE} \le 15V$; $T_j = 150^{\circ}C$; $V_{cc} \le 360V$, use of soft R_G necessary!
- Take care of over-voltage caused by stray inductances



Maximum Ratii	ngs		
Conditions		Values	Unit
•			
T _j = 25 °C		600	V
T 175 °C	T _c = 25 °C	390	Α
-1j - 175 0	T _c = 80 °C	300	А
		300	А
		600	Α
		-20 20	V
$V_{CC} = 360 V$ $V_{GE} \le 15 V$ $V_{CES} \le 600 V$	T _j = 150 °C	6	μs
		-40 175	°C
iode			
T _j = 175 °C	T _c = 25 °C	350	А
	T _c = 80 °C	250	А
		600	А
t _p = 10 ms, sin 180°, T _j = 25 °C		1760	А
		-40 175	°C
		500	А
module without TIM		-40 125	°C
AC sinus 50 Hz, t = 1 min		4000	V
	$\begin{tabular}{ c c c } \hline Conditions \\ \hline T_{j} = 25 \ ^{\circ}C \\ \hline T_{j} = 175 \ ^{\circ}C \\ \hline \\ $	$\begin{array}{c} T_{j} = 25 \ ^{\circ}\text{C} \\ T_{j} = 175 \ ^{\circ}\text{C} \\ \hline T_{c} = 80 \ ^{\circ}\text{C} \\ \hline T_{c} = 80 \ ^{\circ}\text{C} \\ \hline \end{array} \\ \hline \\ V_{CE} = 360 \ V \\ V_{GE} \le 15 \ V \\ V_{CES} \le 600 \ V \\ \hline \end{array} \\ \hline \\ \hline T_{j} = 150 \ ^{\circ}\text{C} \\ \hline \hline \\ T_{c} = 80 \ ^{\circ}\text{C} \\ \hline \hline \\ T_{c} = 80 \ ^{\circ}\text{C} \\ \hline \end{array} \\ \hline \\ \hline \\ t_{p} = 10 \ \text{ms, sin } 180^{\circ}, \ T_{j} = 25 \ ^{\circ}\text{C} \\ \hline \\ \hline \\ \hline \\ module \ without \ TIM \\ \hline \end{array}$	$\begin{tabular}{ c c c c } \hline Conditions & Values \\ \hline $T_j = 25 \ ^{\circ}C$ & $for 00$ \\ \hline $T_j = 175 \ ^{\circ}C$ & $T_c = 25 \ ^{\circ}C$ & 390 \\ \hline $T_c = 80 \ ^{\circ}C$ & 300 \\ \hline $T_c = 80 \ ^{\circ}C$ & 300 \\ \hline 000 & -20 20$ \\ \hline $V_{CC} = 360 \ V$ & $V_{GE} \le 15 \ V$ & $V_{GE} \le 15 \ V$ & $V_{CES} \le 600 \ V$ & $T_j = 150 \ ^{\circ}C$ & 6 \\ \hline $V_{CES} \le 600 \ V$ & $T_j = 150 \ ^{\circ}C$ & 6 \\ \hline $V_{CES} \le 600 \ V$ & $T_j = 150 \ ^{\circ}C$ & 6 \\ \hline $T_j = 175 \ ^{\circ}C$ & $T_c = 25 \ ^{\circ}C$ & 350 \\ \hline $T_c = 80 \ ^{\circ}C$ & 250 \\ \hline $t_p = 10 \ ms, sin 180 \ ^{\circ}, \ $T_j = 25 \ ^{\circ}C$ & 1760 \\ \hline $t_p = 10 \ ms, sin 180 \ ^{\circ}, \ $T_j = 25 \ ^{\circ}C$ & 1760 \\ \hline $t_{centrm{time{time{time{time{time{time{time{tim$

Characteristics								
Symbol	Conditions		min.	typ.	max.	Unit		
IGBT								
V _{CE(sat)}	I _C = 300 A	T _j = 25 °C		1.44	1.85	V		
V _{GE} = 15 V chiplevel	T _j = 150 °C		1.66	2.04	V			
V _{CE0}	chiplevel	T _j = 25 °C		0.90	1.00	V		
		T _j = 150 °C		0.85	0.90	V		
r _{CE} V _{GE} = 15 V chiplevel	V _{GE} = 15 V	T _j = 25 °C		1.8	3	mΩ		
	chiplevel	T _j = 150 °C		2.7	3.8	mΩ		
V _{GE(th)}	$V_{GE} = V_{CE}, I_C = 4.8 \text{ m}$	nA	5	5.8	6.5	V		
I _{CES}	$V_{GE} = 0 V$	T _j = 25 °C		0.15	0.45	mA		
V _{CE} = 600 V	V _{CE} = 600 V	T _j = 150 °C		-		mA		
Cies	V _{CE} = 25 V V _{GE} = 0 V	f = 1 MHz		18.5		nF		
C _{oes}		f = 1 MHz		1.15		nF		
Cres		f = 1 MHz		0.55		nF		
Q _G	V _{GE} = - 8 V+ 15 V			2400		nC		
R _{Gint}	T _j = 25 °C			1.0		Ω		
t _{d(on)}	$\begin{array}{c} V_{CC} = 300 \ V \\ I_C = 300 \ A \\ V_{GE} = +15/-8 \ V \\ R_G \ on = 2.4 \ \Omega \\ R_G \ off = 2.4 \ \Omega \\ di/dt_{on} = 7100 \ A/\mu s \\ di/dt_{off} = 5200 \ A/\mu s \end{array}$	T _j = 150 °C		150		ns		
t _r		T _j = 150 °C		48		ns		
Eon		T _j = 150 °C		7.5		mJ		
t _{d(off)}		T _j = 150 °C		540		ns		
t _f		T _j = 150 °C		53		ns		
E _{off}		T _j = 150 °C		11.5		mJ		
R _{th(j-c)}	per IGBT	I			0.15	K/W		

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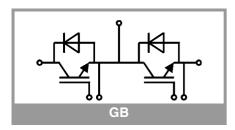
Typical Applications

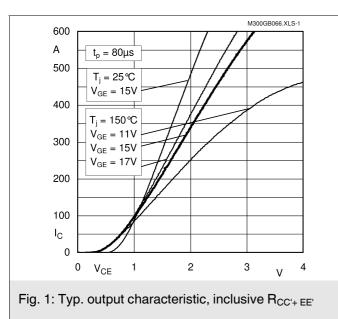
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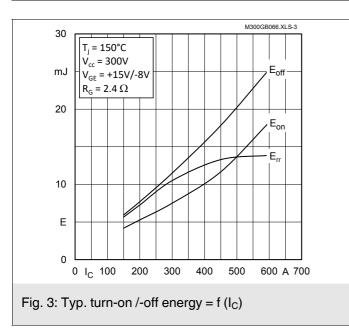
Remarks

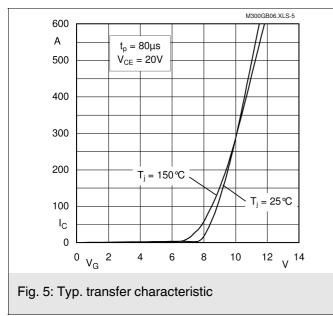
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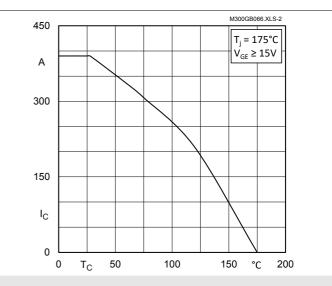
Characte	ristics					
Symbol	Conditions		min.	typ.	max.	Unit
Inverse d	iode					
•F •EC I •	$V_{F} = V_{EC}$ $V_{GE} = 0 V$ $Chiplevel$	T _j = 25 °C	1	1.40	1.6	V
		T _j = 150 °C		-	-	V
V _{F0} chiplevel	chiployol	T _j = 25 °C		0.95	1	V
	chipievei	T _j = 150 °C		-	-	V
r _F chiplevel	chiplevel	T _j = 25 °C		1.5	2	mΩ
		T _j = 150 °C		-	-	mΩ
I _{RRM}	I _F = 300 A	T _j = 150 °C		340		Α
Q _{rr}	di/dt _{off} = 7000 A/µs V _{GF} = -8 V	T _j = 150 °C		47		μC
E _{rr}	V _{CC} = 300 V	T _j = 150 °C		10.5		mJ
R _{th(j-c)}	per diode				0.25	K/W
Module						
L _{CE}				15	20	nH
R _{CC'+EE'}	measured per switch	T _C = 25 °C		0.35		mΩ
		T _C = 125 °C		0.5		mΩ
R _{th(c-s)}	per module			0.02	0.038	K/W
Ms	to heat sink M6		3		5	Nm
Mt		to terminals M6	2.5		5	Nm
				-		Nm
w					325	g

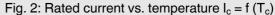


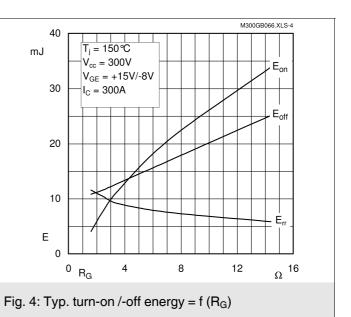


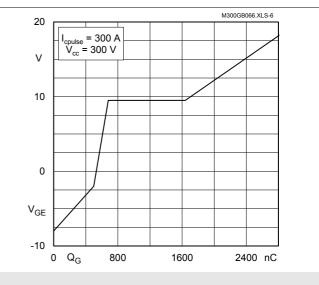


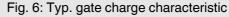












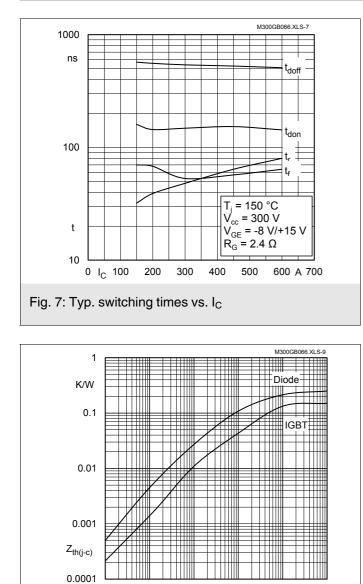
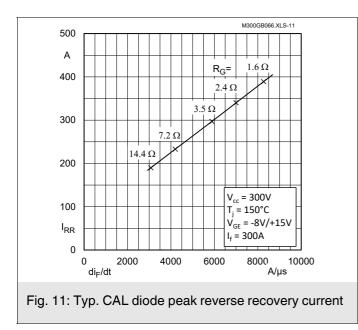


Fig. 9: Transient thermal impedance

0.00001 _{tp} 0.0001

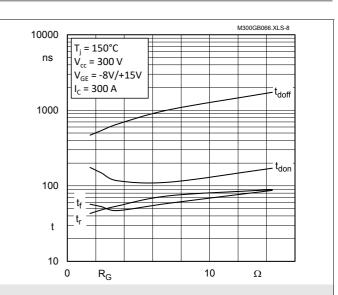


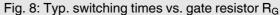
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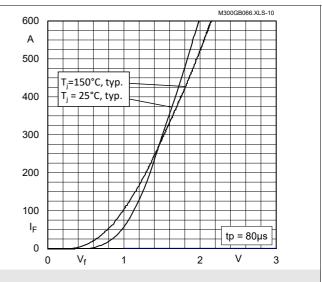
0.01

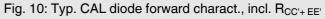
0.1

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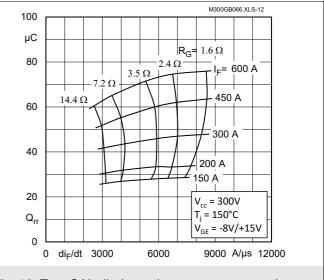
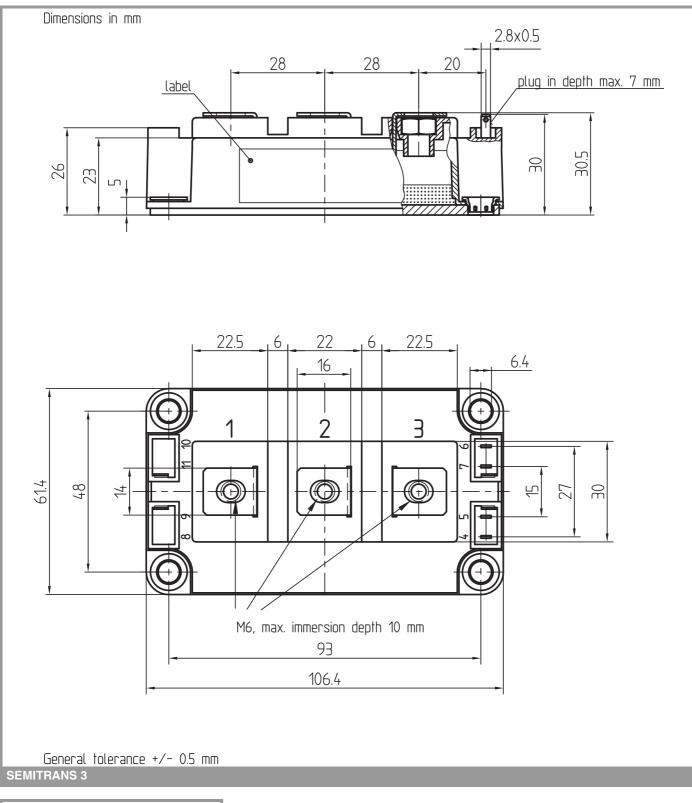
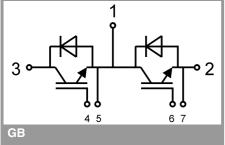


Fig. 12: Typ. CAL diode peak reverse recovery charge





IMPORTANT INFORMATION AND WARNINGS

This is an electrostatic discharge sensitive device (ESDS) according to international standard IEC 61340.

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